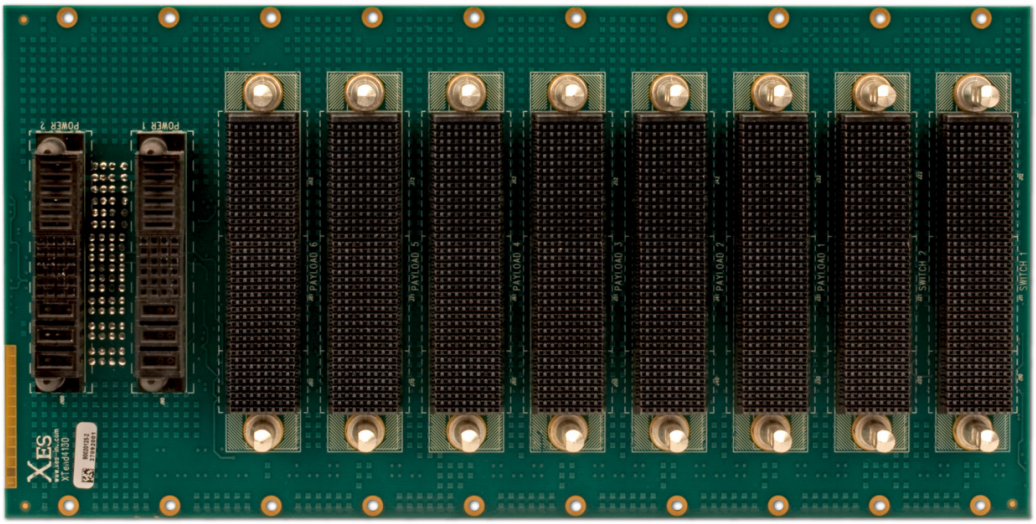
XTend4130

3U VPX Development Backplane with Centralized Switching for Single or Dual Star Topology

- OpenVPX™-compliant
- Six 3U VPX payload slots
- Two 3U VPX switch slots in single or dual star topology
- Two VITA 62.0 power supply slots
- Supports development DC-DC power supply
- Fat Pipe data plane in dual star topology
- Ultra Thin Pipe control plane in dual star topology
- VITA 46.10 RTM support for all payload and switch slots
- 1.0 in. pitch



XTend4130

The XTend4130 is a 3U VPX development backplane designed in accordance with OpenVPX™ system architecture specifications that supports one or two centralized switches for a single or dual star topology. When one switch is used, the XTend4130 provides a single star centralized switching topology. When two centralized switches are installed, the XTend4130 supports redundancy on both the control and data planes with a dual star implementation.

The XTend4130 provides VITA 46.10 RTM connectors for each payload slot and switch slot, and supports up to two parallel VITA 62.0 power supplies. The XTend4130 also supports power sourced from a development DC-DC power supply.

X-ES Extreme Engineering Solutions

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Payload Slots

- Six 3U VPX payload slots
- Two x4 Fat Pipes per slot (data plane)
- Two x1 Ultra Thin Pipes per slot (control plane)

Switch Slots

- Two 3U VPX switch slots
- Six x4 Fat Pipes per slot (data plane)
- Six x1 Ultra Thin Pipes per slot (control plane)
- Single star or dual star redundant switch configuration
- XChange3012-compatible

Power Slots

- Two VITA 62.0 power supply slots
- Supports development DC-DC power supply
- 12 V, 5 V, 3.3 V and ±12 V_AUX, 3.3 V_AUX

VITA 46.10 RTM

- VITA 46.10 Rear Transition Module (RTM) connectors on each payload and switch slot for rear I/O

Bandwidth

- Data plane routing supports up to 8 GBaud transfer rates
- Control plane routing supports up to 8 GBaud transfer rates

Physical Dimension

- 3U VPX form factor
- 129 mm x 258 mm

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1
- Conformal coating available as an ordering option

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g²/Hz (maximum), 5 to 2000 Hz	0.04 g²/Hz (maximum), 5 to 2000 Hz	0.1 g²/Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing